

Covalent Materials Corporation Nissei Bldg, 6-3, Osaki 1-chome, Shinagawa-ku, Tokyo 141-0032, Japan

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[Translation]

October 15, 2012

To Whom It May Concern

Covalent Materials Corporation

Re: Approval of Resolution of the Bondholder's Meeting held concerning

Amendment to the Terms and Conditions (Extension of Maturity Date, Increase in

Interest Rate, Increase in Redemption Amount, etc.) of the 1<sup>st</sup> Series Unsecured

Bonds

The resolution of the bondholders meeting held on October 5, 2012 in relation to the amendment to the terms and conditions of 1st Series Unsecured Bonds of Covalent Materials Corporation (with inter-bond pari passu clause) (ISIN code: JP330135A829) (the "Bonds") has been approved by the Tokyo District Court on October 12, 2012.

Upon such approval, the amendment to the terms and conditions of the Bonds will take effect on October 12, 2012.

\* For inquiries regarding the bondholders meeting:

Accounting & Finance, Finance Group, Covalent Materials Corporation

For English communication, please contact us at the E-mail address below.

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